



CyberOptics Unveils High-Precision 3D XLP Laser Scanning Probes at IMTS

Speeds Attaining Measurement and Inspection Data

Minneapolis, MN— August 30, 2018 — CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces it will unveil 3D XLP Laser Scanning Probes at the International Manufacturing Technology Show, September 10-15 at the McCormick Place, Chicago, Ill. in the Helmel Engineering® booth #135545 East Building.

CyberOptics XLP Laser Scanning Probes provide the industry best accuracy, resolution and speed for 3D laser line scanning. Set-up is fast and easy with automated and programmable three to six-axis scanning capability. Highly accurate data can be quickly attained and analyzed with a comprehensive suite of application tools.

Providing versatility, the XLP Laser Probes are suitable for the factory floor and clean room applications from small, highly detailed parts to large automotive and aerospace parts. The XLP Probes are also integrated with Coordinate Measuring Systems (CMMs) in the company's Surveyor family of 3D Laser Scanning Systems and can be retrofitted to any CMM utilizing Renishaw® UCC2 controllers or other compatible controller.

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About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics' sensors are used in SMT, semiconductor and metrology markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled AOI systems; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 3D CMM system, mid-end semiconductor inspection sensors and CyberGage360 product; costly and time consuming litigation with third parties related to intellectual property infringement; and other factors set forth in the company's filings with the Securities and Exchange Commission.

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